Why Gold for Die-Attach?

- Flux-free high-reliability process
- Highest tensile strength of any solder
- Superior thermal conductivity
- Good joint strength
- High melting point is compatible with subsequent reflow processes
- Resistance to corrosion
- Excellent wetting properties
- Superior thermal fatigue resistance
- Resistance to oxidation
- Pb-free and RoHS compliant

Indalloy®	Composition
200	100Au (1064E)
Braze B962	99.99Ag (962E)
193	72Ag/28Cu (780E)
B6851	63Ag/27Cu/10In (685/730°C)
178	82Au/18In (451-485°C)
NA	96.8Au/3.2Si (363E)
183	88Au/12Ge (356E)
270	75Au/25Sn (278/331°C)
269	78Au/22Sn (278/301°C)
271	79Au/21Sn (278/289°C)
182	80Au/20Sn (278/289°C)

From One Engineer To Another®

Need it Quickly?

Gold Preform Quick Turn Program

Indium Corporation's Gold Preform **Quick Turn** program is designed to get parts in your hands quicker than ever. By doing this, we decrease the time needed to get your project started and increase your production opportunities.

- Designed to deliver parts quickly and affordably
- New design, new tool, prototype quantities in 1–2 weeks
- Engineering support from design to production

Contact our engineers: askus@indium.com
Learn more: www.indium.com

From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

Form No. 99634 R2

High-Reliability Die-Attach Solutions for Laser and RF

Indium Corporation is the leading solder and thermal innovator and supplier for laser and optical applications.

We Believe that
MATERIALS SCIENCE
Changes the World

INDIUM CORPORATION®

High-Reliability Die-Attach Solutions for Laser and RF

Precision Die-Attach (PDA) Preforms

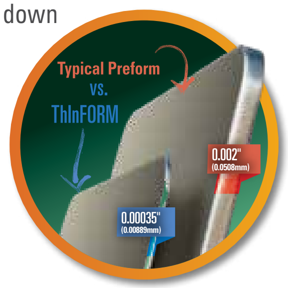
- **Highly accurate thickness control**
- **Precise edge quality**
- **Optimized cleanliness**
- **Default waffle pack**
- **Available for gold-based alloys**

AuLTRA™ 75, 78, 79

- 79Au/21Sn, 78Au/22Sn, and 75Au/25Sn die-attach preforms
- Improve wetting, reduce voiding, and ensure strongest solder bond

AuLTRA™ ThInFORMS™

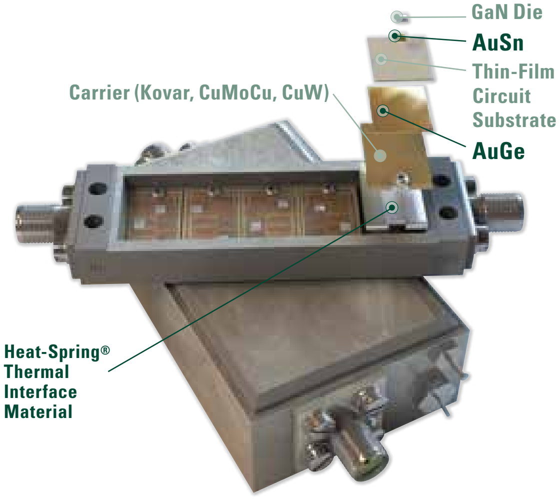
- Precision AuSn die-attach preforms down to 0.00035" (0.00889mm) thickness
- Improve thermal transfer and the control of solder wicking
- Reduce bondline thickness
- Reduce voiding, solder volume



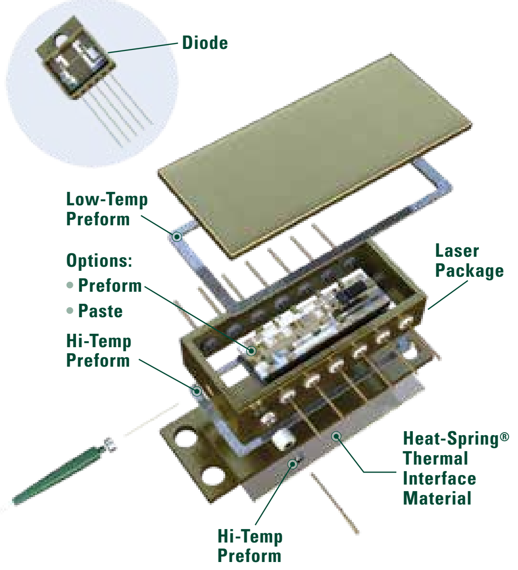
AuLTRA™ Fine Ribbon

- High-quality AuSn ribbon for automated laser diode assembly
- Capability down to 0.010" (0.254mm) wide by 0.0006" (0.01552mm) thick
- >15 meters continuous length
- Au plating available

RF Microwave Packages



Laser & Optical Packaging



Packaging Options

Indium Corporation offers new automated pack solutions for a wide range of die-attach preform dimensions. New **waffle pack** technology is available for both low- and high-volume manufacturing processes. We also can create customized packaging solutions to meet your needs.